

Press Release

C-MAC MicroTechnology and Danfoss Silicon Power announce Design and Manufacturing Partnership

*High-reliability microelectronics specialist and Leading power module supplier join forces to
develop Intelligent Power Modules for the Automotive market*

26 September 2007 – C-MAC MicroTechnology and Danfoss Silicon Power today announced a strategic partnership to co-develop and manufacture intelligent, compact power modules targeted at the rapidly growing Automotive sector. C-MAC MicroTechnology is a world leader in high-reliability electronic systems, modules and components for the Automotive, Aerospace and Defence Electronics markets. Danfoss Silicon Power, a business unit of the Danfoss Group, is a leading global supplier of standard and customized power modules for the Industrial and Automotive markets.

C-MAC and Danfoss will combine their expertise to develop Intelligent Power Modules specifically to meet the demands of modern Automotive applications, where the electronic systems need to be robust, reliable, lightweight and cost effective. C-MAC will primarily provide expertise in the design of the electronic control circuitry, whilst Danfoss will contribute the power electronics. The Automotive market for Intelligent / Integrated Power Modules ('IPMs') is growing strongly, driven by innovative applications such as Electric / Electronic Power Steering, Integrated Starter Alternators and Hybrid Electric Powertrain Controllers¹. These applications are increasing the electrical / electronic content of vehicles and in turn increasing on-board power requirements, creating a demand for integrated power modules capable of rapidly controlling DC and AC motors of up to several thousand watts.

¹ The global demand for hybrid-electric vehicles will grow twenty percent annually through 2010 – Freedonia Market Research.

C-MAC MicroTechnology



Claus Petersen, President of Danfoss Silicon Power said “We are absolutely delighted to be working with C-MAC, their expertise in supplying high-reliability electronics into applications where size, weight and power density are often a constraint, will enable Danfoss Silicon Power to take our existing designs on to a new level of cost/performance, opening up new applications for us.”

Indro Mukerjee, CEO of C-MAC commented “The opportunity to work closely with a company with the pedigree that Danfoss has in the supply of power modules, is extremely exciting. I am confident that the combined expertise of both our companies will result in truly exceptional products, which will further enhance the strong growth we are currently enjoying in our Automotive businesses.”

For further information please contact Ken Henderson, General Manager, C-MAC MicroTechnology at info@cmac.com, or Claus A. Petersen, President Danfoss Silicon Power dsp-info@danfoss.com

NOTES FOR EDITORS:

Danfoss is Denmark’s largest industrial Group with an annual turnover of 2,605 million EUR and about 21,000 employees globally. Danfoss is a global Group and has more than 100 companies around the world. We are among world leaders within research, development and production of mechanical and electronic components for many different sectors. Our position was created by pioneers and developed by visionary and committed employees.

Danfoss Silicon Power, a business unit within the Group, is headquartered in Schleswig, Germany. The business unit develops and produces electronic power modules for many applications, such as frequency converters, power supplies and electronic vehicles. Danfoss Silicon Power has its core competencies within lead-free soldering of large surfaces and unique capabilities within thermal design.

www.danfoss.com

C-MAC MicroTechnology



Headed by Indro Mukerjee, **C-MAC MicroTechnology** is the world leader in the design and manufacture of high reliability hybrid microelectronics solutions. We primarily focus on the automotive, aerospace and defence electronics sectors as well as specialist industrial and medical applications. Our head office is located near London, and we have design and manufacturing facilities in the UK and internationally with dedicated sales and customer support teams throughout Europe and the USA.

C-MAC MicroTechnology offers unrivalled expertise in the design and manufacture of advanced high reliability hybrid microelectronics systems. We specialise in advanced thermal management, high power and high frequency electronic solutions, which are often required to operate in severe environments or extremely confined spaces. Our production sites operate to very high levels of quality including certification to ISO TS16949 and MIL-PRF-38534. Our process technologies include thick-film printing on ceramic and other substrates, surface-mount hybrid circuits, DC/DC power modules, direct-attach flipchip, low-temperature cofired ceramic (LTCC), chip-on-board (COB), multichip module (MCM) assemblies and PCB assembly. These manufacturing resources are complemented by an integrated design-to-test service encompassing ASIC design as well as analogue, digital, RF, mixed-mode and thermal simulation. Through our independently accredited test house facility, we can carry out product qualification and material evaluation to internationally recognized standards.

www.cmac.com

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